

POLISHING DEVICE, POLISHING METHOD, AND RECORDING MEDIUM FOR  
RECORDING PROGRAM FOR DETERMINING SUPPLY POSITION OF POLISHING  
LIQUID

**ABSTRACT**

An operation control unit includes a storage device storing a program which includes commands of: obtaining a correlation between a supply position of the polishing liquid in the radial direction of the polishing pad using the liquid injection nozzle and an average polishing rate of the substrate and an in-plane distribution of the polishing rate of the substrate; determining a movable range of the liquid injection nozzle according to a predetermined range of an allowable average polishing rate and the correlation between the supply position of the polishing liquid and the average polishing rate; determining an optimal supply position of the polishing liquid from the correlation between the supply position of the polishing liquid and the in-plane distribution of the polishing rate of the substrate within the determined movable range of the liquid injection nozzle; and moving the liquid injection nozzle to the determined supply position to polish the substrate.

FIG. 14